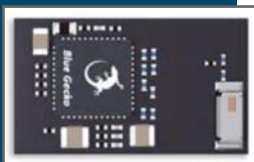
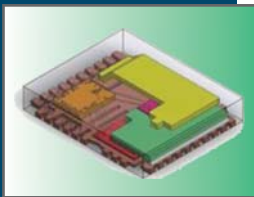
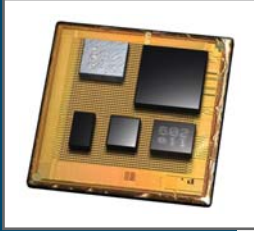


Advanced Packaging Update: Market and Technology Trends

Vol. 3-1017



This issue of the Advanced Packaging Update features special coverage of outsourced assembly and test (OSAT) financials for the first half of the year. A detailed financial analysis of the industry is provided. Drivers for industry growth are discussed and the global economic outlook is presented. A new forecast for the fan-out wafer level package (FO-WLP) market split into high-density and standard-density is presented with explanations for market changes. Company panel FO-WLP activities are included. A section on trends in copper clip packaging, including a market forecast for QFNs with Cu clip is provided. Material developments for Pb-free clip attach are discussed. A discussion on connectivity focused on Wi-Fi modules is included.

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